

Features 特性

- Fast UV cure
快速光固化
- Low temperature cure
低温热固化
- High Tg and low CTE
高 Tg 和低 CTE
- Low shrinkage
低收缩率

Applications Area 应用领域

- Electronic adhesive
电子设备
- Camera module
摄像头模组
- Active alignment
主动对齐

Operating Requirements 操作要求

- Warm up to room temperature
before use
使用前回温到室温
- The reheating needs to be placed
vertically
回温需要垂直放置
- Any moisture should be
immediately wiped off
任何水分应立即擦除
- Cannot be repeatedly frozen
不能反复冷冻

- **2501-AA** 是一种高性能的紫外光和热双重固化胶粘剂，具有低温快速固化、低热膨胀系数、高玻璃化转变温度等特点， 同时具有出色的粘结强度以及优异的耐热和耐湿性能。
- **2501-AA** is a high-performance adhesive with UV and heat dual-curing property. It features rapid curing at low temperatures, low CTE and High Tg. Additionally, it offers excellent bonding strength along with outstanding heat and moisture resistance.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成份	Silica powder filled epoxy 氧化硅粉体填充环氧树脂		—
Color 颜色	半透明凝胶	—	Visual 目视
Viscosity 粘度	45000	mPa·s	25°C
Density 密度	1.6	g/cm³	ASTM D1875
Cure schedule 固化条件	3-10s@400mw/cm²	—	
	50min@85°C	—	
Hardness 硬度	90	Shore D	ASTM D2240
Tensile strength 拉伸强度	35	MPa	ASTM D638
Elongation at break 断裂伸长率	1.1	%	ASTM D638
Water absorption 吸水率	0.12	%	ASTM D570
Volumetric Shrinkage 体积收缩率	1.2	%	Internal Standard
Tg 玻璃化转变温度	160	°C	DMA
CTE1	40	ppm/K	TMA
CTE2	70	ppm/K	TMA
Tensile Modulus 弹性模量	5000	MPa	@ 25°C by DMA
Adhesion shear strength (PC-PC) 粘接强度	30	MPa	Internal Standard
Pot life 使用时间	3	Days	@25°C
Shelf life 储存时间	180	Days	@-20°C
RoHS Compliance 合规性	YES	—	—

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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